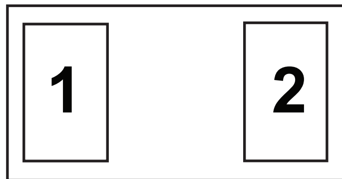
HF RoHS Pb GREEN SP1007 Lead-Free/Green Series

Description

The SP1007 includes back-to-back Zener diodes fabricated in a proprietary silicon avalanche technology to provide protection for electronic equipment that may experience destructive electrostatic discharges (ESD). These robust diodes can safely absorb repetitive ESD strikes at the maximum level specified in the IEC61000-4-2 international standard (Level 4, ±8kV contact discharge) without performance degradation. The back-to-back configuration provides symmetrical ESD protection for data lines when AC signals are present.

Pinout

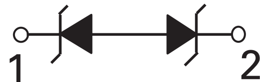


Note: Drawing not to scale.

Features

- ESD, IEC61000-4-2, ±8kV contact, ±15kV air
- EFT, IEC61000-4-4, 40A (5/50ns)
- Lightning, IEC61000-4-5, 2A (t_P=8/20μs)
- Low capacitance of 3.5pF (@ V_R=2.5V)
- Low leakage current of 0.1μA at 5V
- Industries smallest ESD footprint available (0201)

Functional Block Diagram



Applications

- Mobile phones
- Smart phones
- Camcorders
- PDA
- Digital cameras
- MP3/PMP
- Portable navigation devices
- Portable medical
- Point of sale terminals

Life Support Note:

Not Intended for Use in Life Support or Life Saving Applications

The products shown herein are not designed for use in life sustaining or life saving applications unless otherwise expressly indicated.

Downloaded from Elcodis.com electronic components distributor

Absolute Maximum Ratings

Symbol	Parameter	Value	Units
I_{PP}	Peak Current (t_p=8/20μs)	2.0	A
T_{OP}	Operating Temperature	-40 to 85	°C
T_{STOR}	Storage Temperature	-65 to 150	°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Thermal Information

Parameter	Rating	Units
Storage Temperature Range	-65 to 150	°C
Maximum Junction Temperature	150	°C
Maximum Lead Temperature (Soldering 10s)	260	°C

Electrical Characteristics (T_{OP}=25°C)

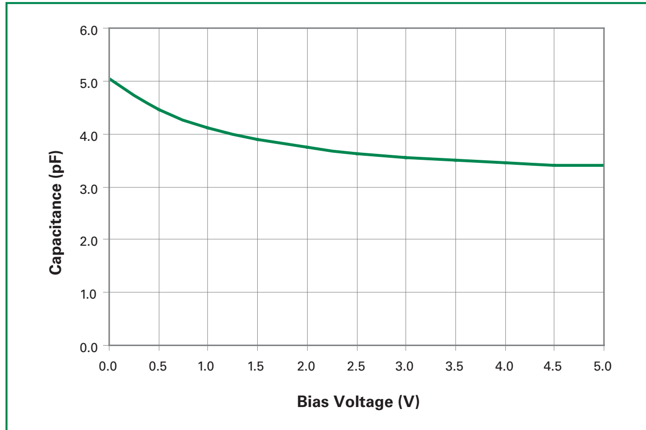
Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Reverse Standoff Voltage	V_{RWM}				6.0	V
Breakdown Voltage	V_{BR}	I_R=1mA		8.5	9.5	V
Leakage Current	I_{LEAK}	V_R=5V with 1 pin at GND		0.1	0.5	μA
Clamp Voltage[1]	V_C	I_{PP}=1A, t_p=8/20μs, Fwd		10.3		V
		I_{PP}=2A, t_p=8/20μs, Fwd		12.2		V
Dynamic Resistance	R_{DYN}	$(V_{C2} - V_{C1}) / (I_{PP2} - I_{PP1})$		1.9		Ω
ESD Withstand Voltage[1]	V_{ESD}	IEC61000-4-2 (Contact Discharge)	±8			kV
		IEC61000-4-2 (Air Discharge)	±15			kV
I/O to I/O Capacitance[1]	$C_{I/O-I/O}$	Reverse Bias=0V		5	6	pF
		Reverse Bias=2.5V		3.5		pF

NOTES:
[1]Parameter is guaranteed by design and/or device characterization.

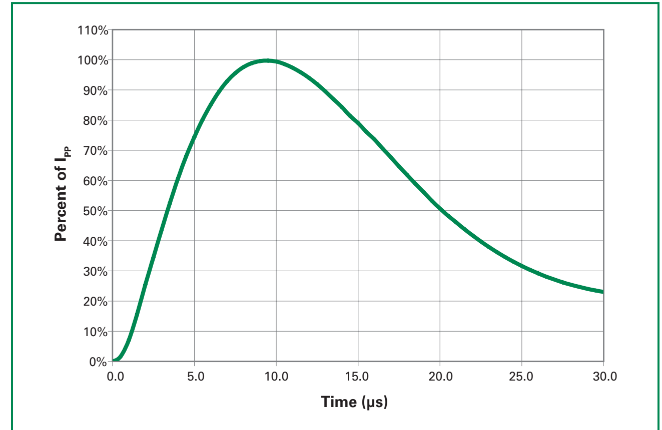
©2010 Littelfuse, Inc.
Specifications are subject to change without notice.
Please refer to http://www.littelfuse.com for current information.

Downloaded from Elcodis.com electronic components distributor

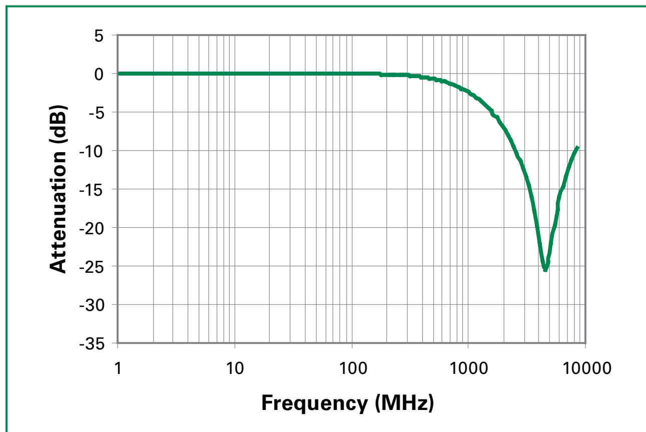
Capacitance vs. Reverse Bias



Pulse Waveform



Insertion Loss (S21) I/O to GND

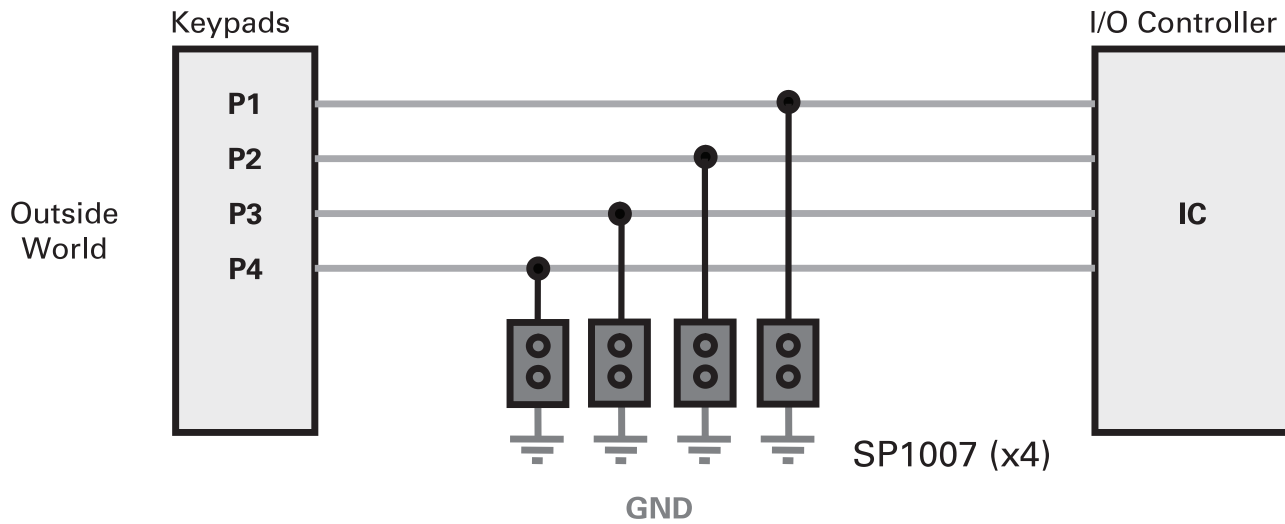


©2010 Littelfuse, Inc.

Specifications are subject to change without notice.
Please refer to http://www.littelfuse.com for current information.

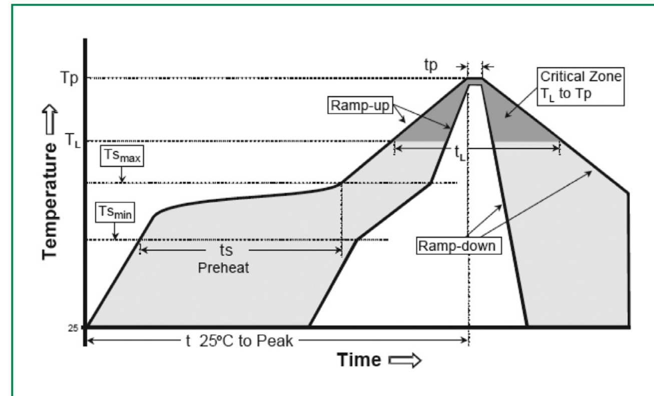
Downloaded from Elcodis.com electronic components distributor

Application Example



Soldering Parameters

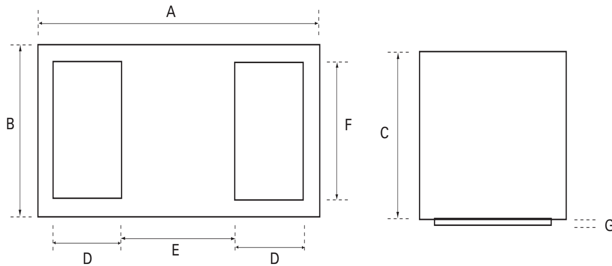
Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus) Temp (T_L) to peak		3°C/second max
$T_{S(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_P)		$250^{+0/-5}$ °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max.
Do not exceed		260°C



©2010 Littelfuse, Inc.
Specifications are subject to change without notice.
Please refer to http://www.littelfuse.com for current information.

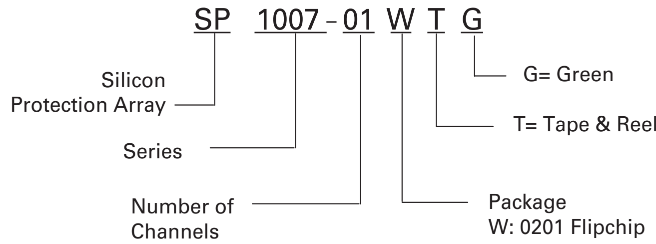
Downloaded from Elcodis.com electronic components distributor

Package Dimensions - 0201 Flip Chip



Symbol	0201 Flipchip					
	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
A	0.595	0.620	0.645	0.0234	0.0244	0.0254
B	0.295	0.320	0.345	0.0116	0.0126	0.0136
C	0.245	0.275	0.305	0.0096	0.0108	0.0120
D	0.145	0.150	0.155	0.0057	0.0059	0.0061
E	0.245	0.250	0.255	0.0096	0.0098	0.0100
F	0.245	0.250	0.255	0.0096	0.0098	0.0100
G	0.005	0.010	0.015	0.0002	0.0004	0.0006

Part Numbering System



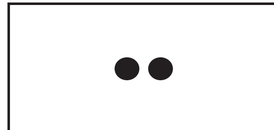
Product Characteristics

Lead Plating	Sn
Lead Material	Copper
Lead Coplanarity	6 um (max)
Subsitute Material	Silicon
Body Material	Silicon

Notes :

1. All dimensions are in millimeters
2. Dimensions include solder plating.
3. Dimensions are exclusive of mold flash & metal burr.
4. All specifications comply to JEDEC SPEC MO-223 Issue A
5. Blo is facing up for mold and facing down for trim/form, i.e. reverse trim/form.
6. Package surface matte finish VDI 11-13.

Part Marking System



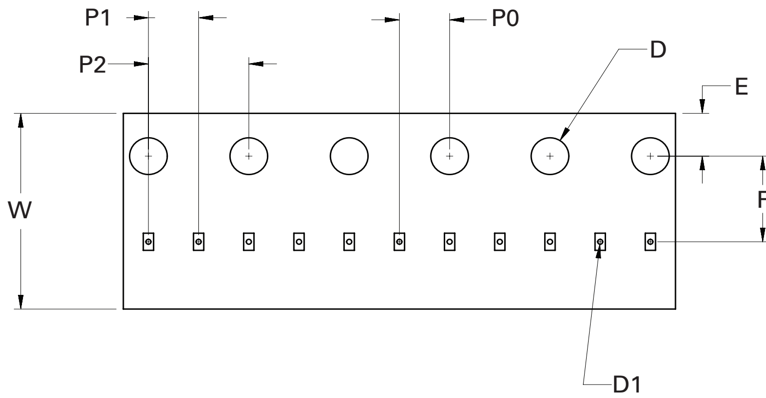
Ordering Information

Part Number	Package	Marking	Min. Order Qty.
SP1007-01WTG	0201 Flipchip	• •	10000

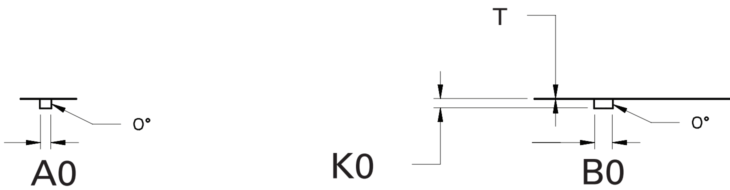
©2010 Littelfuse, Inc.
Specifications are subject to change without notice.
Please refer to http://www.littelfuse.com for current information.

Downloaded from Elcodis.com electronic components distributor

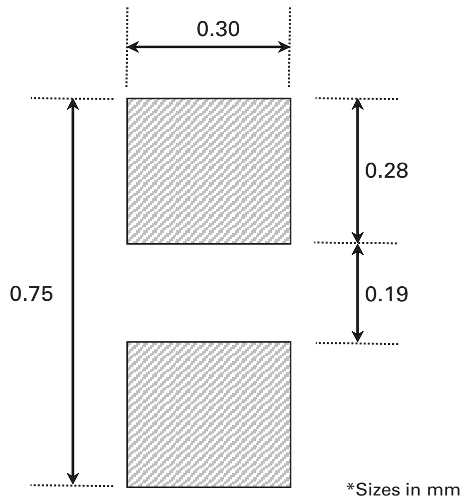
Embossed Carrier Tape & Reel Specification – 0201 Flipchip



Symbol	Millimeters
A0	0.41+/-0.03
B0	0.70+/-0.03
D	ø 1.50 + 0.10
D1	ø 0.20 +/- 0.05
E	1.75+/-0.10
F	3.50+/-0.05
K0	0.38+/-0.03
P0	2.00+/-0.05
P1	2.00+/-0.05
P2	4.00+/-0.10
W	8.00 + 0.30 -0.10
T	0.23+/-0.02



Recommended Solder Pad Footprint



*Sizes in mm

©2010 Littelfuse, Inc.
Specifications are subject to change without notice.
Please refer to http://www.littelfuse.com for current information.

Downloaded from Elcodis.com electronic components distributor